Amendment to Claims

Please cancel claims14-21, without prejudice, as shown below.

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1. (Original) A non-volatile memory package comprising:

a substrate having a first surface and a second surface;

an integrated circuit die including a memory array mounted to the first surface of the substrate; and

a1 a passive component mounted to the second surface of the substrate.

2. (Original) The non-volatile memory package of claim 1, wherein the passive component is electrically coupled to the integrated circuit die.

3. (Original) The non-volatile memory package of claim 1, further comprising an array of solder balls mounted to the substrate.

4. (Original) The non-volatile memory package of claim 3, wherein the passive component is located centrally within the array of solder balls.

5. (Original) The non-volatile memory package of claim 4, wherein the passive component has a height less than a height of the solder balls.

6. (Original) The non-volatile memory package of claim 1, wherein the passive component is at least a portion of a voltage regulator circuit coupled to the integrated circuit die.

7. (Original) The non-volatile memory package of claim 1, wherein the substrate comprises a cavity and at least a portion of the passive component lies within the cavity.

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8. (Original) The non-volatile memory package of claim 7, further comprising an array of solder balls mounted to the substrate, wherein the passive component has a height less than a height of the solder balls.

9.
~~10.~~ (Original) The non-volatile memory package of claim 1, wherein the passive component is mounted to the second surface of the substrate with an epoxy material.

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10.
~~11.~~ (Original) The non-volatile memory package of claim 9 ~~10~~, wherein the epoxy material between the passive component and the substrate is less than about 0.1 millimeters in thickness.

11.
~~12.~~ (Original) The non-volatile memory package of claim 1, wherein the passive component is mounted to the substrate with a conductive material.

12.
~~13.~~ (Original) Th non-volatile memory package of claim 1, wherein the passive component includes a capacitor or an inductor.

13. ~~14.~~ (Original) The memory device of claim 1, wherein the integrated circuit die includes a flash memory array.

14. ~~13.~~ (Cancelled) A method comprising:

forming a substrate;

mounting an integrated circuit die on said substrate;

mounting a passive component overly the substrate; and

electrically coupling the passive component to at least a portion of the integrated circuit die.

15. ~~14.~~ (Cancelled) The method of claim 12 ~~13~~, further comprising adhesively attaching the passive component to he integrated circuit die.

16. ~~15.~~ (Cancelled) The method of claim 13 ~~14~~, further comprising adhesively attaching the passive component to the integrated circuit die with a non-conductive adhesive.

17. ~~16.~~ (Cancelled) The method of claim 12 ~~13~~ including wire bonding the passive component to the substrate.

18. ~~17.~~ (Cancelled) The method of claim 12 ~~13~~ including wire bonding the passive component to the integrated circuit die.

19.
~~18~~. (Cancelled) A method comprising:

molding an integrated circuit die and at least one passive component to a voltage regulator circuit into a package, the integrated circuit die including a non-volatile memory array.

Cancelled A1

20.
~~19~~. (Cancelled) The method of claim ~~18~~ 19, further comprising mounting the at least one passive component to the integrated circuit die.

21.
~~20~~. (Cancelled) The method of claim ~~18~~ 19, further comprising forming a wire bond to electrically couple the at least one passive component and the integrated circuit.